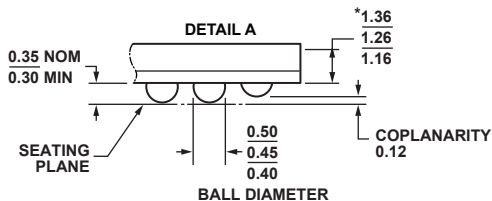
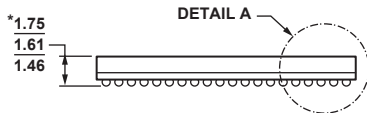
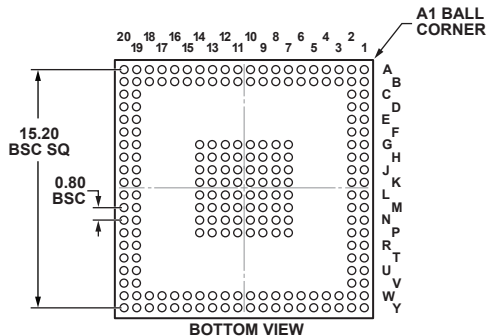
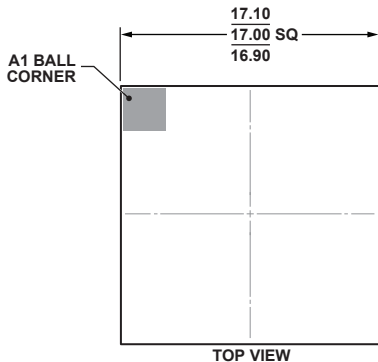


**208-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-208-2)**

Dimensions shown in millimeters



***COMPLIANT TO JEDEC STANDARDS MO-275-MMAB-1 WITH
EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.**